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FOR IMMEDIATE RELEASE

Press Release

SEMICON WEST 2018 starts next Tue July 10th! VISIT YINCAE BOOTH 5269

(Albany, NY) July 3, 2018 – SEMICON West 2018, North America’s premier Microelectronics event, is just one week away! The show will be held at the Moscone Center in San Francisco, CA from July 10th to 12th. YINCAE sincerely invites you to stop by our Booth #**5269** to speak with our experts and to see what’s new.

We are noticing an emerging trend in underfill and thermal materials and would love to showcase a wide range of materials varying from the World’s first commercial diamond underfill, to a high filler-load underfill that can flow into small gaps at room temperature, a solder joint encapsulant paste that has low temperature reflow and high pull strength at high temperature (300°C), a reflowable (filled) underfill that is excellent for applications with a narrow footprint and lastly, a mold underfill with a 90% filler load able to flow into 25µm gap without external force.

These are the materials you need and YINCAE Advanced Materials, LLC hopes that you are finalizing preparation for the SEMICON WEST 2018. We are looking forward to seeing you in the **Moscone Center at booth 5269** and will be available to talk about our products and answer any inquiries you may have. We hope that you will join us at the conference to learn about our exclusive products that no other company offers. We look forward to seeing you at booth 5269!

If you wish to schedule a booth meeting,
please email us at info@yincae.com or call (518) 452-2880

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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